

Sb δ -doping of non-degenerate Ge(001) for a spin-FET with a high-mobility channel

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Introduction

Spin-dependent transport in a lateral semiconductor (SC) channel with two ferromagnetic (FM) contacts is the fundamental operation principle of the spin field-effect-transistor (spin-FET). For an effective transport of the spin-polarized carriers, the use of a non-degenerate SC is desirable because longer spin lifetimes are expected. The major requirement to employ a non-degenerate SC channel is to suppress the thermionic emission current and enhance the tunneling transport across the FM/SC contact by reducing the depletion region width in the SC region [1]. Recently, Hamaya and his co-workers have developed low-resistance FM tunnel contacts on *n*-type non-degenerate Ge(111) using the Sb δ -doping and low-temperature Ge homoepitaxy [2, 3]. On the other hand, Ge(001) is also a promising candidate as a channel of the spin-FET since epitaxial FM/MgO(001) tunnel barrier can be easily grown, providing a canonical spin injector/detector. Here, we have investigated the effect of the Sb δ -doping on the electrical transport process of Fe/MgO/non-degenerate Ge(001) devices.

Sample preparations

Films were grown by molecular beam epitaxy on *n*-type Ge(001) substrates (a carrier concentration of $\sim 5 \times 10^{16} \text{ cm}^{-3}$). Sb was evaporated at room temperature (RT), followed by a 10 nm-thick Ge layer. We prepared several samples with different sheet doping densities of Sb (n_{Sb}) and growth temperature (T_g) of the homoepitaxial Ge layer. Finally, Au(20 nm) / Fe(5 nm) / MgO(1.5 nm) layers were deposited at RT. Reflection high-energy electron diffraction (RHEED) image revealed that the MgO layers have (001)-oriented single-crystalline or textured structure depending on T_g and n_{Sb} .

Results

Figure 1(a) shows the current-voltage (I - V) characteristics of the devices grown at different T_g with a constant $n_{\text{Sb}} = 2.0 \times 10^{14} \text{ cm}^{-2}$. The devices with $T_g = 400 \text{ }^\circ\text{C}$ and $350 \text{ }^\circ\text{C}$ reveal a clear rectifying behavior, showing that the thermionic emission is the dominant transport process. With decreasing T_g , the current under reverse bias dramatically increases, and the rectifying behavior finally disappears above $T_g = 250 \text{ }^\circ\text{C}$. For the devices with $T_g = 250 \text{ }^\circ\text{C}$ and $200 \text{ }^\circ\text{C}$, there is no large difference in the resistance-area products (RA) as plotted in Fig.1 (b). This indicates that tunneling becomes the major transport process for $T_g \leq 250 \text{ }^\circ\text{C}$.

References

- [1] R. Jansen and B. C. Min, Phys. Rev. B **99**, 246604 (2007). [2] K. Sawano *et al.*, Appl. Phys. Lett. **97**, 162108 (2010). [3] K. Kasahara *et al.*, J. Appl. Phys. **111**, 07C503 (2012).

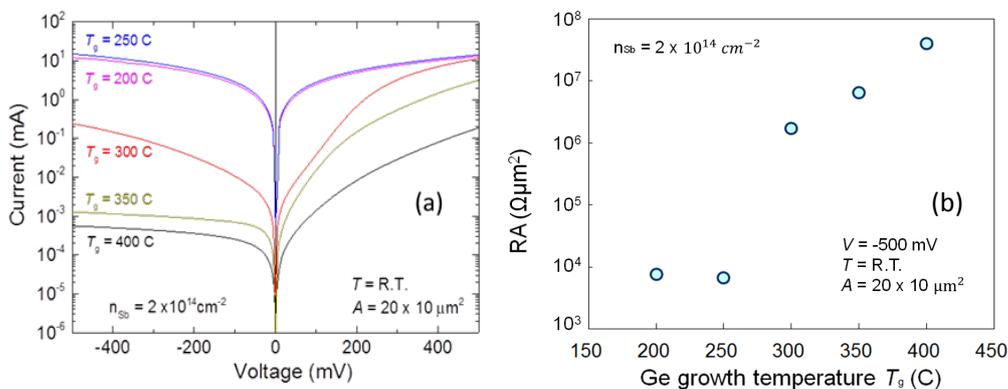


Fig.1 (a) Current-voltage characteristics of Fe/MgO/*n*-Ge(001) devices and (b) the corresponding RA at -500 mV as a function of T_g measured at RT. The sheet Sb doping density n_{Sb} is kept constant with a $2.0 \times 10^{14} \text{ cm}^{-2}$.